



SMB

Plastic, surface-mounted package; 2 terminals;
4.32 mm x 3.62 mm x 2.3 mm body

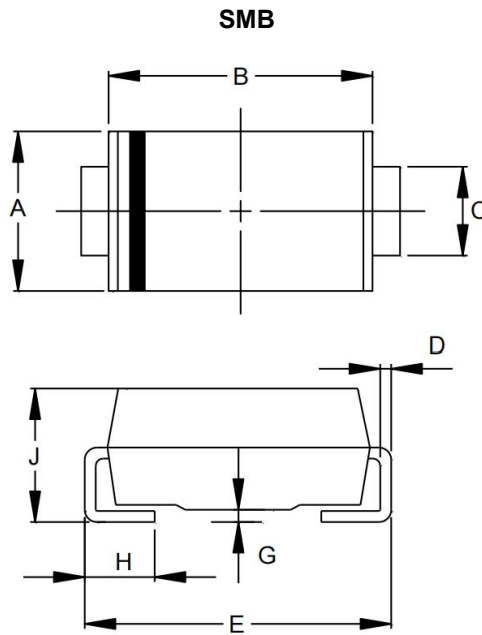
塑料表面贴装封装；2 引脚；

封装本体尺寸 4.32 mm x 3.62 mm x 2.3 mm

1. Mechanical Data 封装数据

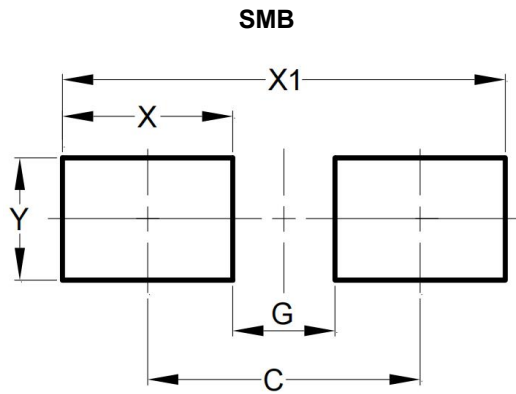
Feature 特性	Description 描述
Package 封装	SMB(DO-214AA)
Moisture Sensitivity Level 湿敏感度等级	J-STD-020 MSL1
Mounting Method Type 安装方式类型	Surface Mount Package 表面贴装封装
Material 材料	Molded Plastic, “Green” Molding Compound; UL Flammability Classification Rating 94V-0. 模塑塑料封装，“绿色”成型复合材料；UL 可燃性等级 94V-0。
Dimensions 尺寸	4.32mm × 3.62mm × 2.3mm body 封装本体（不含引脚）尺寸为 4.32mm × 3.62mm × 2.3mm
Terminals Compliance 引脚合规	2 terminals, Tin Plated Leads, Solderable per MILSTD-202, Method 208 ^③ 2 个镀锡引脚，可焊性符合 MIL-STD-202 标准中 208 方法 e3 条款的要求
Weight 重量	0.1 grams (Approximate) 约 0.1 克

2. Package Outline Dimensions 封装外形尺寸



Symbol 符号	Millimeters 毫米	
	Min.最小值	Max.最大值
A	3.30	3.94
B	4.06	4.70
C	1.91	2.11
D	0.15	0.31
E	5.08	5.59
G	-	0.203
H	0.76	1.27
J	2.13	2.44

3. Suggested Pad Layout 推荐焊盘布局



Dimensions 尺寸	Millimeters 毫米
C	4.3
G	1.8
X	2.5
X1	6.8
Y	2.3

Fig. Soldering footprint for SMB

图 SMB 的引脚焊接

4. Minimum Packing Quantity 最小包装数量

Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
13	12	3000

Note:

Package quantities given are for minimum packaging quantity only, not minimum order quantity. For minimum order quantity, please contact Sales Department.

说明: 上表所列包装数量仅为最低包装数量，并非最低订购数量。如需最低订购数量，请联系销售部门。



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Date of release: 26 Dec 2025

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发布日期：2025-12-26
